

### LISTING OF THE CLAIMS

A detailed listing of claims is presented below. Please amend currently amended claims as indicated below including substituting clean versions for pending claims with the same number. In addition, clean text versions of pending claims not being currently amended that are under examination are also presented. It is understood that any claim presented in a clean version below has not been changed relative to the immediate prior version.

20. (Currently Amended) A multilayer electrode for a flat panel display device, said multilayer electrode comprising:

a metal alloy layer, wherein said metal alloy layer includes neodymium having a concentration of between greater than three atomic percent and six atomic percent; and

a protective layer disposed above said metal alloy layer to form a multilayer stack, said multilayer stack etched to form said multilayer electrode, wherein said protective layer includes an molybdenum tungsten alloy.

21. (Original) The multilayer electrode for a flat panel display device as recited in Claim 20, wherein said metal alloy layer is comprised of aluminum and neodymium.

22. (Original) The multilayer electrode for a flat panel display device as recited in Claim 20, wherein said

metal alloy layer has a depth of approximately 2500 angstroms.

23. (Currently Amended) The multilayer electrode for a flat panel display device as recited in Claim 20, wherein said ~~protective layer is comprised of molybdenum and tungsten~~ molybdenum tungsten alloy in said protective layer includes a tungsten concentration of 5 to 30 atomic percent.

24. (Original) The multilayer electrode for a flat panel display device as recited in Claim 20, wherein said protective layer has a depth of approximately 1200 angstroms.

47. (Currently Amended) A multilayer electrode for a flat panel display device, said multilayer electrode comprising:

a metal alloy layer, wherein said metal alloy layer includes neodymium having a concentration of between greater than three atomic percent and six atomic percent;

a barrier layer disposed above said metal alloy layer;  
and

a protective layer disposed above said metal alloy layer to form a multilayer stack, said multilayer stack etched to form said multilayer electrode, wherein said protective layer includes an molybdenum tungsten alloy.

48. (Original) The multilayer electrode for a flat panel display device as recited in Claim 47, wherein said metal alloy layer is comprised of aluminum and neodymium.

49. (Original) The multilayer electrode for a flat panel display device as recited in Claim 47, wherein said metal alloy layer has a depth of approximately 2500 angstroms.

50. (Original) The multilayer electrode for a flat panel display device as recited in Claim 47, wherein said barrier layer is comprised of a native oxide layer of said metal alloy layer.

51. (Original) The multilayer electrode for a flat panel display device as recited in Claim 47, wherein said barrier layer has a depth of less than approximately 100 angstroms.

52. (Original) The multilayer electrode for a flat panel display device as recited in Claim 47, wherein said ~~protective layer is comprised of molybdenum and tungsten~~ molybdenum tungsten alloy in said protective layer includes a tungsten concentration of 5 to 30 atomic percent.

53. (Original) The multilayer electrode for a flat panel display device as recited in Claim 47, wherein said protective layer has a depth of approximately 1200 angstroms.

54. (Original) The multilayer electrode for a flat panel display device as recited in Claim 47, wherein said multilayer electrode is etched using a wet etchant with volume percentages of constituents of approximately 70-80 percent  $\text{H}_3\text{PO}_4$ ; approximately 10-15 percent  $\text{HNO}_3$ ; approximately 7-12 percent  $\text{CH}_3\text{COOH}$ ; and approximately 2-8 percent  $\text{H}_2\text{O}$  to form a desired sloped profile.

55. (New) A multilayer electrode for a flat panel display device, said multilayer electrode comprising:

a metal alloy layer, wherein said metal alloy layer includes a silver alloy; and

a protective layer disposed above said metal alloy layer to form a multilayer stack, said multilayer stack etched to form said multilayer electrode.

56. (New) The multilayer electrode of Claim 55, wherein said silver alloy comprises:

silver;

palladium having a concentration of 0.5 to 2 atomic percent; and

copper having a concentration of 0.5 to 2 atomic percent.

57. (New) The multilayer electrode of Claim 55,  
wherein said silver alloy comprises:

silver;

palladium having a concentration of 0.5 to 2 atomic  
percent; and

titanium having a concentration of 0.0 to 2.0 atomic  
percent.